



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	27-07-2017
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	MDG MD CHAMPION	<b>Representative Title</b>	MDG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

**Legal Statement**


<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
------------------------------	------	----------------------------	----------

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F302RET6 STM32F302RET6TR	S55W*446XXXY	A	998Z	27-07-2017
Amount	UoM	Unit type	ST ECOPACK Grade	
357,39	mg	Each	ECOPACK® 2	
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		


  
 life.augmented

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L Bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	555W*446000Y				6000000.0	0.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	22,597	mg	supplier	die	Silicon (Si)	7440-21-3		21,674	mg	959154	60645
				supplier	metallization	Aluminium (Al)	7429-90-5		0,063	mg	2788	176
				supplier	metallization	Copper (Cu)	7440-50-8		0,313	mg	13851	876
				supplier	metallization	Cobalt (Co)	7440-48-4		0,058	mg	2567	162
				supplier	metallization	Titanium (Ti)	7440-32-6		0,017	mg	752	48
				supplier	metallization	Tungsten (W)	7440-33-7		0,034	mg	1505	95
				supplier	Passivation	Silicon Nitride	12033-89-5		0,041	mg	1814	115
				supplier	Passivation	Silicon Oxide	7631-86-9		0,397	mg	17569	1111
Die Attach Epoxy_ABLEBOND 3230_H	M-011 Other inorganic materials	2,381	mg	Supplier	Metals	Silver	7440-22-4		2,145	mg	901000	6002
				Supplier	Plastics/polymers	Highly cross-linked polymer	Proprietary		0,236	mg	99000	660
Mold Compound_EME-G631SHQ_Sun	M-011 Other inorganic materials	233,088	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		5,002	mg	21000	13995
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		5,002	mg	21000	13995
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		13,338	mg	56000	37321
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		180,794	mg	780450	-494129
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		27,467	mg	115320	76855
Wire_AG SI TYPE_MKE	Bonding Wire	0,389	mg	Supplier	Non-metals	Carbon Black	1333-86-4		1,484	mg	6230	4152
				Supplier	Metals	Silver	7440-22-4		0,373	mg	960000	1044
				Supplier	Metals	Others	Proprietary		0,016	mg	40000	44
Plating anode_Pure Tin_Nuo Nengda	M-011 Other inorganic materials	1,438	mg	Supplier	Metals	Tin	7440-31-5		1,438	mg	1000000	4023
Leadframe_C9+Ag_HDS	Copper & its alloys	97,500	mg	Supplier	Metals	Iron	7439-89-6		2,132	mg	21865	5965
				Supplier	Non-metals	Phosphorus	7723-14-0		0,071	mg	730	199
				Supplier	Metals	Zinc	7440-66-6		0,110	mg	1125	307
				Supplier	Metals	Copper	7440-50-8		89,040	mg	913235	249139
				Supplier	Metals	Silver	7440-22-4		6,143	mg	63000	17187
				JIG-R	Metals	Lead	7439-92-1		0,004	mg	45	12